

Amendments to the Specification

After the title, please insert the following paragraph:

B1 -- This application claims the benefit of U.S. Provisional Application No. 60/245,308, filed on November 2, 2000. --

Please replace the paragraph beginning at page 11, line 22, with the following:

B2 -- The present copper electroplating compositions are suitably used in similar manner as prior copper electroplating baths. Plating baths of the invention are preferably employed at or above room temperature, e.g. up to 65° C and greater. The plating composition is preferably agitated during use such as by air sparger, work piece agitation, impingement or other suitable method. Plating is preferably conducted at a current density ranging from 1 to 40 ASF depending upon substrate characteristics. Plating time may range from about 5 minutes to 1 hour or more, depending on the difficulty of the work piece. --